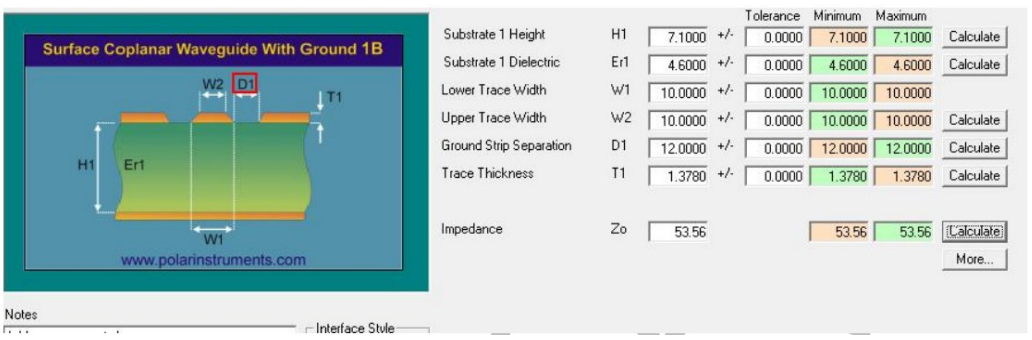
Shenzhen YanPoDo Technology Co.,Ltd

Guide for RF outgoing line stacking of double-layer board module:

If there is no requirement for the line width, double layers of plates can be used. The line width is generally 30 mil, the ground covering distance is 7 mil, the plate thickness is 1.6 mm, and the line route is as short as possible to ensure the integrity of the reference ground plane.

Guide for the stacking of RF outgoing lines of four-layer board module:
Unit mil



The figure above shows the data calculated by SI9000 by selecting the coplanar waveguide single-end impedance model.
Lamination requirements: the lamination thickness between the two layers of the RF line reference layer is 7.87mi1, i.e. 0.2m (including the thickness of glue pressing, and the PP layer is calculated according to 7.1mil (H1)), which generally refers to the thickness of the dielectric layer 1 and 2 and the thickness of the dielectric layer 3 and 4. The integrity of the RF outgoing line reference ground plane shall be ensured when other layers are routed.
Note: Different plates will affect the dielectric constant, thus affecting the characteristic impedance. Jialichuang or Jiepai are recommended. The cost of good plates is on the high side, which is not applicable. The RF line width is 10mil (w1), and the ground wire spacing (D1) is 12mil The outer layer is 10Z thick and the inner layer is 0 50Z。